

General Description

The WST06P06 is the highest performance trench P-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WST06P06 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

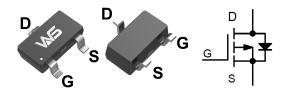
Product Summery

BVDSS	RDSON	ID
-60V	80mΩ	-5.5A

Applications

- Brushless motor
- Load switch
- Uninterruptible power supply

SOT-23-3L PiN Configuration



Absolute Maximum Ratings

Symbol	<u>Parameter</u>	Rating	Units
V_{DS}	Drain-Source Voltage	-60	V
V_{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25℃	Continuous Drain Current, -V _{GS} @ -10V ¹	-5.5	Α
I _D @T _C =100°C	Continuous Drain Current, -V _{GS} @ -10V ¹	-3.5	А
I _{DM}	Pulsed Drain Current ²	-20	А
EAS	Single Pulse Avalanche Energy ³	15	mJ
I _{AS}	Avalanche Current	-20	Α
P _D @T _C =25°C	Total Power Dissipation⁴	1.5	W
T _{STG}	Storage Temperature Range	-55 to 150	$^{\circ}$
TJ	Operating Junction Temperature Range -55 to 150		$^{\circ}$

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹		125	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		80	°C/W



P-Channel Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25℃, I _D =-1mA		-0.012		V/°C
D	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-3A		80	90	mΩ
R _{DS(ON)}	Static Dialii-Source Off-Resistance	V _{GS} =-4.5V , I _D =-2A		100	150	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} . In =-250uA	-1.2	-1.75	-2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} -V _{DS} , I _D 250uA		4.32		mV/℃
-	Drain Course Leglage Current	V _{DS} =-32V , V _{GS} =0V , T _J =25°C			1	uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-32V , V _{GS} =0V , T _J =55°C			5	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20 V$, V_{DS} = $0 V$			±100	nA
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		13	16	Ω
Q_g	Total Gate Charge (-4.5V)			12.4		
Q_gs	Gate-Source Charge	V _{DS} =-20V , V _{GS} =-4.5V , I _D =-3A		2.2		nC
Q_gd	Gate-Drain Charge			6.3		
$T_{d(on)}$	Turn-On Delay Time			9.2		
Tr	Rise Time	V_{DD} =-15V , V_{GS} =-10V , R_{G} =3.3 Ω ,		20.1		ns
$T_{d(off)}$	Turn-Off Delay Time	I _D =-1A		46.7		115
T_f	Fall Time			9.4		
C _{iss}	Input Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		1137		
C _{oss}	Output Capacitance			76		pF
C _{rss}	Reverse Transfer Capacitance			50]

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =-25V , L=0.1mH , I _{AS} =-24A	10			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			-5	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25℃			-1.2	V

Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V DD =-25V,V GS =-10V,L=0.1mH,IAS =-24A
- 4. The power dissipation is limited by 150 ℃ junction temperature
- 5. The data is theoretically the same as I D and I DM, in real applications, should be limited by total power dissipation.

P-Channel Typical Characteristics

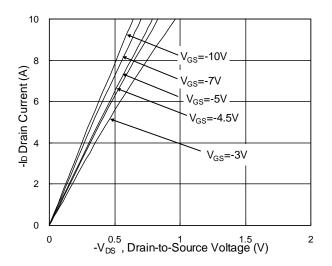


Fig.1 Typical Output Characteristics

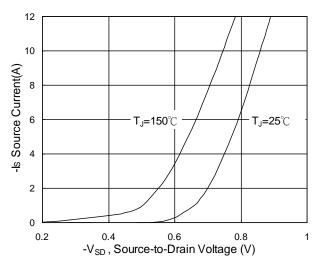


Fig.3 Forward Characteristics of Reverse

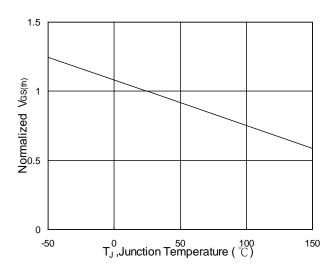


Fig.5 Normalized V_{GS(th)} v.s T_J

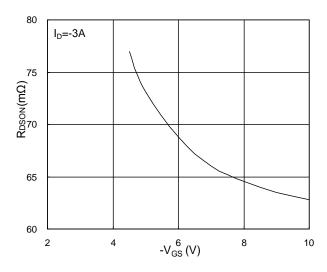


Fig.2 On-Resistance v.s Gate-Source

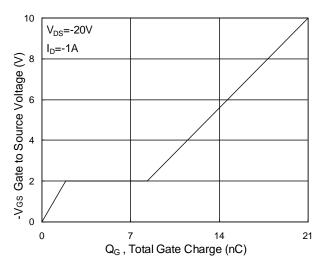


Fig.4 Gate-Charge Characteristics

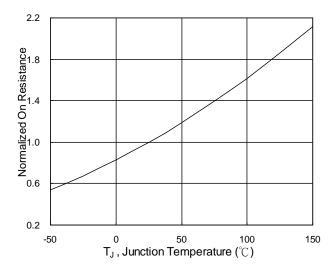
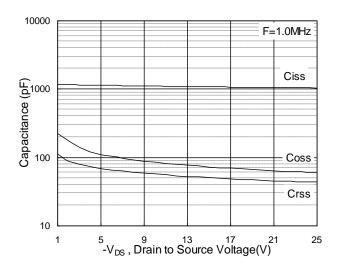


Fig.6 Normalized R_{DSON} v.s T_J





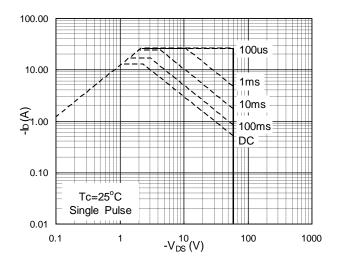


Fig.7 Capacitance

Fig.8 Safe Operating Area

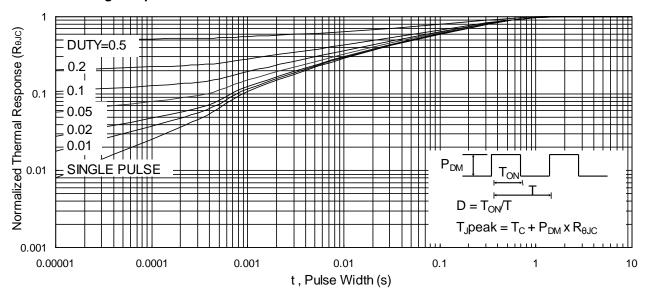
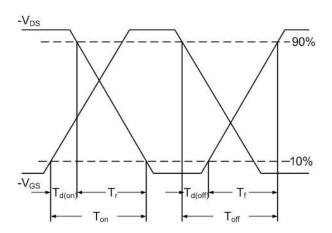
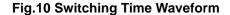


Fig.9 Normalized Maximum Transient Thermal Impedance





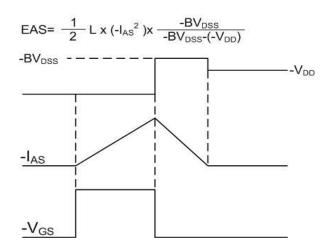


Fig.11 Unclamped Inductive Switching Waveform



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